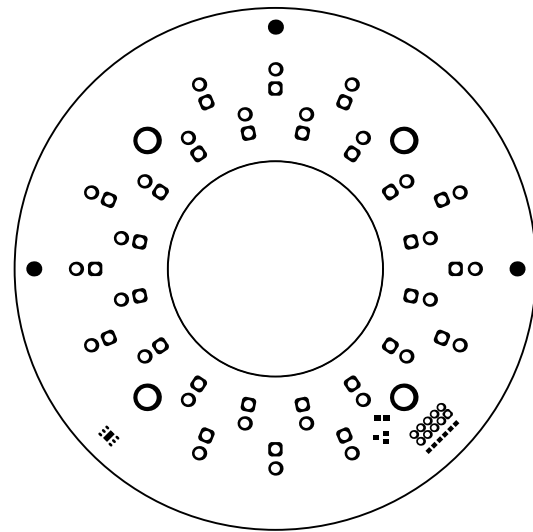
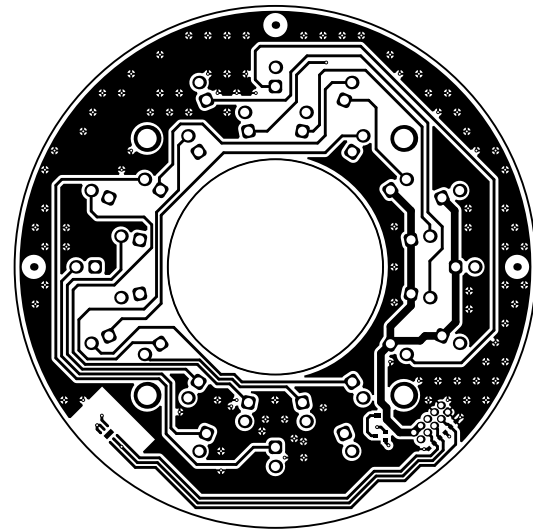


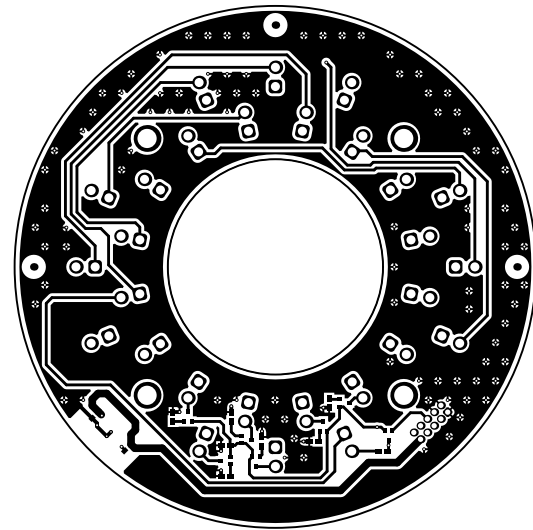
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01586	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay	TID #: TIDA-01586 Board 1		
PLOT NAME = Top Overlay	GENERATED : 2/2/2018	10:22:54 AM	TEXAS INSTRUMENTS



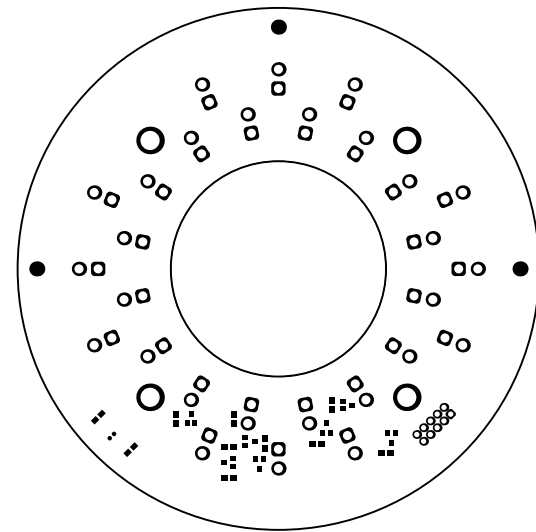
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01586	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Solder	TID #: TIDA-01586 Board 1		
PLOT NAME = Top Solder Mask	GENERATED : 2/2/2018 10:22:55 AM	TEXAS INSTRUMENTS	



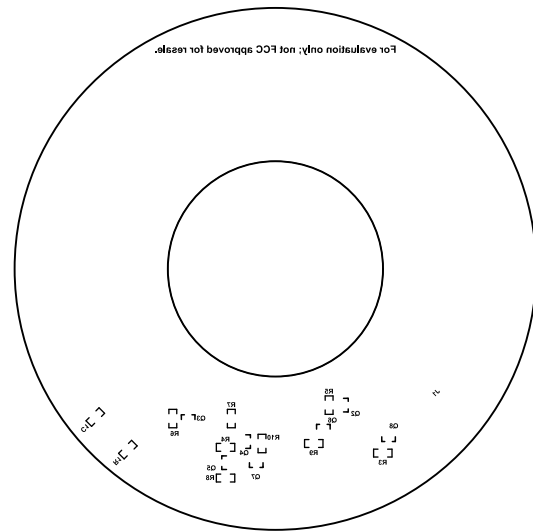
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01586	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Layer 1 - Top Layer	TID #: TIDA-01586 Board 1		
PLOT NAME = Top Layer	GENERATED : 2/2/2018	10:22:55 AM	TEXAS INSTRUMENTS



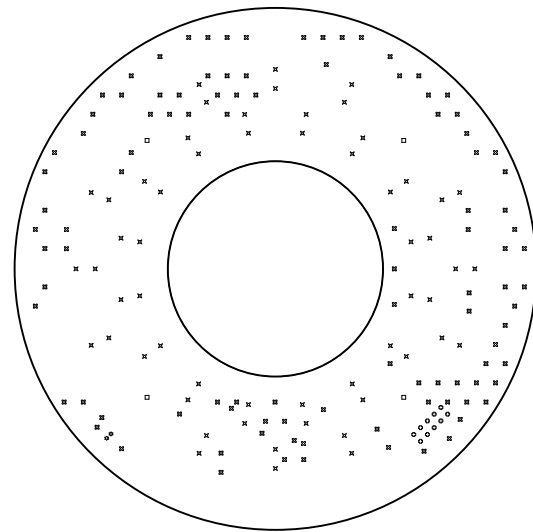
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01586	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Layer 2 - Bottom Layer	TID #: TIDA-01586 Board 1		
PLOT NAME = Bottom Layer	GENERATED : 2/2/2018	10:22:56 AM	TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01586	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder	TID #: TIDA-01586 Board 1		
PLOT NAME = Bottom Solder Mask	GENERATED : 2/2/2018 10:22:57 AM	TEXAS INSTRUMENTS	

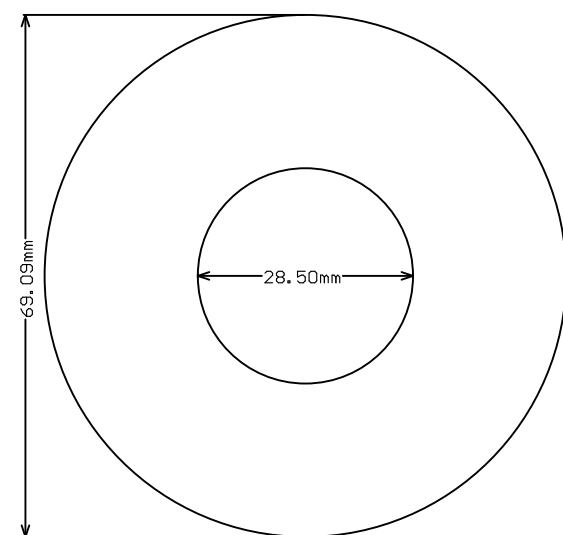


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01586	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay	TID #: TIDA-01586 Board 1		
PLOT NAME = Bottom Overlay	GENERATED : 2/2/2018	10:22:58 AM	TEXAS INSTRUMENTS



Symbol	Quantity	Finished Hole Size	Plated	Hole Type	Drill Layer Pair	Hole Tolerance
⊗	2	7.87mil (0.200mm)	PTH	Round	Layer 1 - Top Layer - Layer 2 - Bottom Layer	
⊗	102	10.00mil (0.254mm)	PTH	Round	Layer 1 - Top Layer - Layer 2 - Bottom Layer	
⊗	10	27.56mil (0.700mm)	PTH	Round	Layer 1 - Top Layer - Layer 2 - Bottom Layer	
⊗	56	47.24mil (1.200mm)	PTH	Round	Layer 1 - Top Layer - Layer 2 - Bottom Layer	
□	4	100.00mil (2.540mm)	PTH	Round	Layer 1 - Top Layer - Layer 2 - Bottom Layer	
	174 Total					

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01586	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing	TID #: TIDA-01586 Board 1		
PLOT NAME = Drill Drawing	GENERATED : 2/2/2018	10:22:59 AM	TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01586	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions	TID #: TIDA-01586 Board 1		
PLOT NAME = Board Dimensions	GENERATED : 2/2/2018	10:23:00 AM	TEXAS INSTRUMENTS

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